



(11) **EP 1 759 810 B8**

(12) **CORRECTED EUROPEAN PATENT SPECIFICATION**

(15) Correction information:  
**Corrected version no 1 (W1 B1)**  
**Corrections, see**  
**Bibliography INID code(s) 84**

(51) Int Cl.:  
**B24B 37/04 (2006.01) B24B 41/06 (2006.01)**

(48) Corrigendum issued on:  
**18.11.2009 Bulletin 2009/47**

(45) Date of publication and mention  
of the grant of the patent:  
**07.10.2009 Bulletin 2009/41**

(21) Application number: **06254557.9**

(22) Date of filing: **31.08.2006**

(54) **Wafer polishing method**

Verfahren zum Polieren von Halbleiterscheiben

Méthode de polissage de plaquette

(84) Designated Contracting States:  
**DE FR GB NL**

(30) Priority: **31.08.2005 JP 2005251026**

(43) Date of publication of application:  
**07.03.2007 Bulletin 2007/10**

(73) Proprietor: **Shin-Etsu Chemical Co., Ltd.**  
**Tokyo (JP)**

(72) Inventors:  
• **Murai, Toshinari c/o Shin-Etsu Chemical Co., Ltd.**  
**Joetsu-shi, Niigata-ken (JP)**

• **Shibano, Yukio c/o Shin-Etsu Chemical Co., Ltd.**  
**Joetsu-shi, Niigata-ken (JP)**

(74) Representative: **Stoner, Gerard Patrick et al**  
**Mewburn Ellis LLP**  
**33 Gutter Lane**  
**London**  
**EC2V 8AS (GB)**

(56) References cited:  
**EP-A- 1 298 713 JP-A- 62 297 064**  
**JP-A- 63 093 562 US-A- 4 466 852**  
**US-A- 5 906 532**

Note: Within nine months of the publication of the mention of the grant of the European patent in the European Patent Bulletin, any person may give notice to the European Patent Office of opposition to that patent, in accordance with the Implementing Regulations. Notice of opposition shall not be deemed to have been filed until the opposition fee has been paid. (Art. 99(1) European Patent Convention).

**EP 1 759 810 B8**